



# **SPECIFICATION**

(Reference sheet)

- Supplier : Samsung electro-mechanics - Samsung P/N : CL10C180JB8NNND

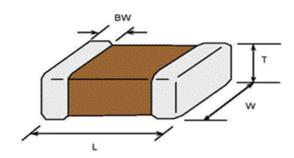
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 18pF, 50V, ± 5%, C0G, 0603

### A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>180</u> <u>J</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>D</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| ① Series   | Samsung Multi-layer | Samsung Multi-layer Ceramic Capacitor |                          |  |  |  |
|------------|---------------------|---------------------------------------|--------------------------|--|--|--|
| ② Size     | 0603 (inch code     | e) L: 1.60 ± 0.10 mm                  | W: 0.80 ± 0.10 mm        |  |  |  |
| ③ Dielecti | ric C0G             | 8 Inner electrode                     | Ni                       |  |  |  |
| 4 Capacit  | ance 18 pF          | Termination                           | Cu                       |  |  |  |
| ⑤ Capacit  | ance ± 5 %          | Plating                               | Sn 100% (Pb Free)        |  |  |  |
| toleran    | ce                  | Product                               | Normal                   |  |  |  |
| 6 Rated V  | <b>/oltage</b> 50 V | Special                               | Reserved for future use  |  |  |  |
| 7 Thickne  | ess 0.80 ± 0.10 mm  | ① Packaging                           | Cardboard Type, 13" reel |  |  |  |

#### **B. Structure and dimension**



| Samsung P/N     | Dimension(mm) |             |             |             |
|-----------------|---------------|-------------|-------------|-------------|
| (Lead Free)     | L             | W           | Т           | BW          |
| CL10C180JB8NNND | 1.60 ± 0.10   | 0.80 ± 0.10 | 0.80 ± 0.10 | 0.30 ± 0.20 |

#### C. Samsung Reliability Test and Judgement condition

|                   | Performance   | Test condition                        |  |  |  |
|-------------------|---|---------------------------------------|--|--|--|
| Capacitance       | Within specified tolerance  | 15ñ10% 0.5~5Vrms                      |  |  |  |
| Q                 | 760 min   |                                       |  |  |  |
| Insulation        | 10,000Mohm or 500Mohm×μF  | Rated Voltage 60~120 sec.             |  |  |  |
| Resistance        | Whichever is smaller  |                                       |  |  |  |
| Appearance        | No abnormal exterior appearance                                   | Microscope (´10)                      |  |  |  |
| Withstanding      | No dielectric breakdown or  | 300% of the rated voltage             |  |  |  |
| Voltage           | mechanical breakdown  |                                       |  |  |  |
| Temperature C0G   |   |                                       |  |  |  |
| Characteristics   | (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃) |                                       |  |  |  |
| Adhesive Strength | No peeling shall be occur on the                                  | 500g×F, for 10±1 sec.                 |  |  |  |
| of Termination    | terminal electrode  |                                       |  |  |  |
| Bending Strength  | Capacitance change :  | Bending to the limit (1mm)            |  |  |  |
|                   | within ±5% or ±0.5pF whichever is larger                          | with 1.0mm/sec.                       |  |  |  |
| Solderability     | More than 75% of terminal surface                                 | SnAg3.0Cu0.5 solder                   |  |  |  |
|                   | is to be soldered newly   | 245±5℃, 3±0.3sec.                     |  |  |  |
|                   |   | (preheating : 80~120 ℃ for 10~30sec.) |  |  |  |
|                   |   |                                       |  |  |  |
| Resistance to     | Capacitance change :  | Solder pot : 270±5℃, 10±1sec.         |  |  |  |
| Soldering heat    | within ±2.5% or ±0.25pF whichever is larger                       |                                       |  |  |  |
|                   | Tan δ, IR : initial spec.   |                                       |  |  |  |
| Vibration Test    | Capacitance change :  | Amplitude: 1.5mm                      |  |  |  |
|                   | within ±2.5% or ±0.25pF whichever is larger                       | From 10Hz to 55Hz (return : 1min.)    |  |  |  |
|                   | Tan δ, IR : initial spec.   | 2hours ´ 3 direction (x, y, z)        |  |  |  |
| Moisture          | Capacitance change :  | With rated voltage                    |  |  |  |
| Resistance        | within ±7.5% or ±0.75pF whichever is larger                       | 40±2℃, 90~95%RH, 500+12/-0hrs         |  |  |  |
|                   | Q: 160 min  |                                       |  |  |  |
|                   | IR: 500Mohm or 25Mohm × μF  |                                       |  |  |  |
|                   | Whichever is smaller  |                                       |  |  |  |
| High Temperature  | Capacitance change :  | With 200% of the rated voltage        |  |  |  |
| Resistance        | within ±3% or ±0.3pF whichever is larger                          | Max. operating temperature            |  |  |  |
|                   | Q: 320 min  | 1000+48/-0hrs                         |  |  |  |
|                   | IR: 1,000Mohm or 50Mohm × $\mu$ F                                 |                                       |  |  |  |
|                   | Whichever is smaller  |                                       |  |  |  |
| Temperature       | Capacitance change :  | 1 cycle condition                     |  |  |  |
| Cycling           | within ±2.5% or ±0.25pF whichever is larger                       | Min. operating temperature → 25 °C    |  |  |  |
| -                 | Tan δ, IR : initial spec.   | → Max. operating temperature → 25°C   |  |  |  |
|                   |   |                                       |  |  |  |
|                   |   |                                       |  |  |  |
|                   |   | 5 cycle test                          |  |  |  |

<sup>\*</sup> The reliability test condition can be replaced by the corresponding accelerated test condition.

#### D. Recommended Soldering method:

Reflow (Reflow Peak Temperature: 260+0/-5°C, 10sec. Max)

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

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- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- Military equipment
- 5 Disaster prevention/crime prevention equipment
- Any other applications with the same as or similar complexity or reliability to the applications set forth above.